

# 2027 HSPA Conference Scholarship Application

The HSPA Foundation, HSPA's philanthropic arm, was created to provide valuable education and support to Sterile Processing (SP) professionals through educational initiatives, research, scholarships, professional development grants, and awards.

The HSPA Foundation will provide 11 scholarships for the 2027 HSPA Conference at the Greater Columbus Convention Center in Columbus, Ohio. (April 24–27, 2027). The Foundation will provide 11 scholarships, including one scholarship in honor of Anne Cofiell. Anne was a loyal supporter of the SP profession who advocated tirelessly about the critical importance of safe, high-quality medical device processing—beginning with effective, thorough and consistent cleaning. She was an active member of HSPA and served on AAMI working groups throughout her long career.

The scholarships will cover the conference registration fee and hotel accommodations for up to four nights. *Note: transportation and other incurred expenses are not included.*

## Scholarship & Submission Requirements:

- Applicant must be currently employed in a Sterile Processing/Central Service or material management department
- Applicant must provide demonstrated commitment to continuing education and best practices
- Applicant must be a certified technician (CRCST, CER, CSPDT or CFER)
- Applicant must submit the scholarship application along with a letter of recommendation from a current supervisor/manager **on company letterhead**
- Application must be submitted by **November 6, 2026**

*(Please note: any applications that do not meet the above criteria will not be accepted).*

## SECTION 1 — APPLICANT INFORMATION

Date: \_\_\_\_\_

First and Last Name of Applicant: \_\_\_\_\_

Title/Job Position: \_\_\_\_\_

Place of Employment/Company Name: \_\_\_\_\_

Phone: \_\_\_\_\_

Email: \_\_\_\_\_

☐ CRCST    ☐ CER    ☐ CSPDT    ☐ CFER

HSPA ID# (if applicable): \_\_\_\_\_

Have you attended the HSPA Conference in the past?:    ☐ YES    ☐ NO

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## SECTION 2 — **ESSAY**

*(You may insert your responses to the questions below on this form or submit a separate document).*

1) Why do you want to attend the 2027 HSPA Conference? (min. 100 words)

## SECTION 3 — **SUBMISSION CHECKLIST**

- \_\_\_ Scholarship Application
- \_\_\_ Letter of reference from a current supervisor/manager **on company letterhead**
- \_\_\_ Essay – Minimum of 100 words

### **Send to:**

**Mail:** HSPA Foundation Scholarships  
55 West Wacker Drive  
Suite 501  
Chicago, IL 60601

**Fax:** 312.440.9474

**Email:** [foundation@myhspa.org](mailto:foundation@myhspa.org)